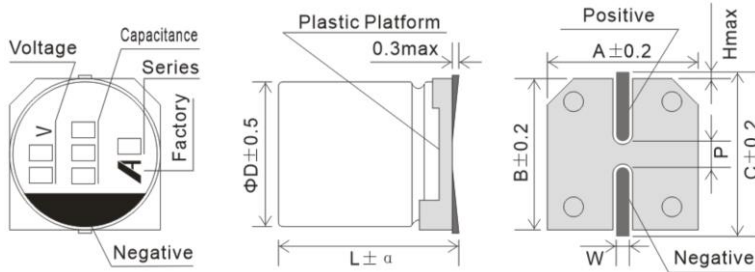


■ Description 产品描述:
Al-Ecap, 330uF, 35v, ±20%, D8H10.5mm, 2000Hrs@105℃, -55~+105℃, SMD.

■ Dimension& Marking 印刷及尺寸:

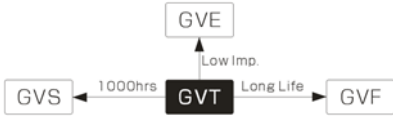


■ Features 特长/用途:

- 105℃, 2,000 hours assured 宽温长寿命
- Designed for surface mounting on high density PC board 适合高密度表面安装

■ Serie Expansion 系列拓展

Items Case	A	B	C	D	P	L	α	W	H
Φ8x10.5	8.3	8.3	9	8.0	3.1	10.5	±0.5	0.8~1.1	0.5max.

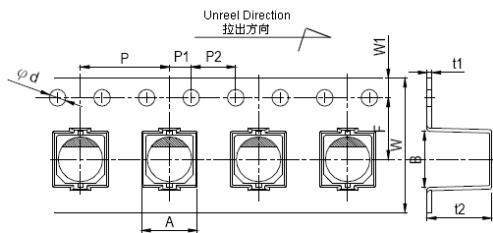


Items 项目	Performance 性能			
Rated Voltage 额定电压(V _R)	35 V			
Capacitance 额定容量(C _R)	330 uF (120Hz, 20℃)			
Category Temperance Range 类别温度范围	-55℃ ~ +105℃			
Capacitance Tolerance 容量误差	-20% ~ +20% (120Hz, 20℃)			
Surge Voltage 浪涌电压(V _S)	40.3 V _{DC}			
Leakage Current 泄漏电流(I _{LC})	I _{LC} ≤ 115.5 uA After 2 minutes			
Dissipation Factor (Tanδ) 损失角正切值	≤ 0.16 (120Hz, 20℃)			
Ripple Current 纹波电流(I _{RC} , rms)	225 mA (120Hz, 105℃)			
Low Temperature Characteristics 温度特性(120Hz)	Impedance ratio 阻抗比(Max.)	Z _(-25℃) / Z _(+20℃)	2	
		Z _(-55℃) / Z _(+20℃)	3	
Endurance and Shelf Life 耐久性及高温无负荷特性	Items 项目	Endurance 耐久性		Shelf Life Test 高温无负荷
	Test Time 测试时长	2,000 Hrs at 105℃; V _R		1,000 Hrs at 105℃
	Cap. Change 容量变化率	Within ±30% of initial Value ≤ 初始值的±30%		Within ±30% of initial Value ≤ 初始值的±30%
	Tanδ 损失角正切值	Less than 300% of specified Value ≤ 初始规格值的±300%		Less than 300% of specified Value ≤ 初始规格值的±300%
	Leakage Current 漏电流	Whitin specified Value ≤ 初始规格值		Whitin specified Value ≤ 初始规格值
Ripple Current and Frequency Multipliers 纹波电流频率系数	Frequency (Hz)	50, 60	120	1k
	Multiplier	0.80	1.00	1.20
Standards 参考标准	JIS C 5101-1, -18, IEC 60384-4			
Remarks 附注	RoHS Compliance, Halogen-free			

* Please refer to "Precautions and Guidelines for Aluminum Electrolytic Capacitors" section in catalog for further details 详细信息请参阅目录中的“铝电解电容器注意事项和指南”

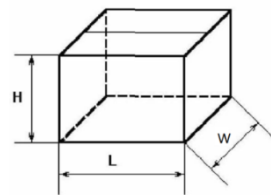
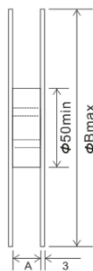
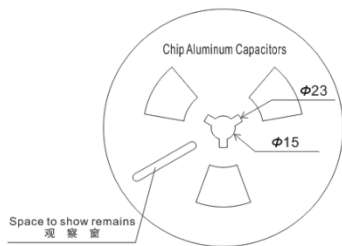
Publication Date 发行日期	2022-02-15	Approved 批准 	Checked 复核	Designed 设计
Revision Date 修订日期			Lei Yang	Chao Yu
Version No.	1.0			

■Taping Specifications 编带规格:



Case 尺寸	W (mm)	W1 (mm)	F (mm)	P (mm)	P1 (mm)	P2 (mm)	A (mm)	B (mm)	t1 (mm)	t2 (mm)
Tolerance 误差	±0.3	±0.15	±0.1	±0.1	±0.1	±0.1	±0.2	±0.2	±0.1	±0.2
Φ8x10.5	24	1.75	11.5	16	2	4	8.7	8.7	0.4	11

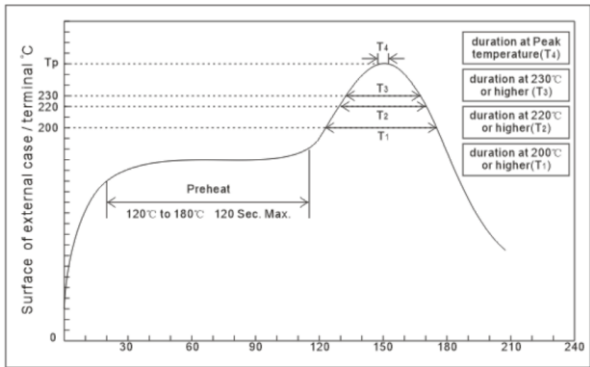
■ Park 包装:



Case 产品尺寸	Reel 卷装数量	Box 盒装数量	A±0.3(mm)	B±2(mm)	Box size 外箱尺寸(L*W*H)
Φ8x10.5	500	5000	26	382	395x305x395

■ Soldering Conditions 焊接条件:

- he following conditions are recommended for air convection and infrared reflow soldering on the SMD products onto a glass epoxy circuit boards by cream solder. The temperatures shown are the surface temperature values on the top of the can and on the capacitor terminals. 当使用回流焊，在玻璃环氧树脂基板上进行焊接的时候，产品顶部及端子部分温度，时间的推荐范围如下表所示。
- Reflow should be performed twice or less 推荐回流次数不超过 2 次。
- Please ensure that the capacitor became cold enough to the room temperature (5 to 35℃) before the second reflow. 请在第 1 次回流之后，必须确保电容器的温度已经完全冷却到室温(5~35℃)后方可进行第 2 次回流。



Note 备注:

- Average ramp-up rate is 5℃/second max
温度上升平均每秒钟最多 5℃；
- Ramp-down rate is 6℃/second max
温度下降平均每秒钟最多 6℃；
- Time from 25℃ to peak temperature is 6 minutes max.
从 25℃上升到峰值温度的时间最多 6 分钟；

Catgeory 类别	Time maintained above 200℃(T1) 200℃以上时间	Time maintained above 217℃(T2) 217℃以上时间 (T2)	Time maintained above 230℃(T3) 230℃以上时间(T3)	Range of Peak 峰值范围		Relow number 回流焊次数
				Temp 温度	Times 时间	
Φ8	90 sec.	60 sec.	40 sec.	255℃ Max.	5sec Max.	2 times or less